TPS254900 - Legacy BC1.2 Controller

TUSB213 - USB 2.0 Redriver with DC Boost

TUSB319 - USB Type-C Negotiator

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LM74610 - Reverse Battery Protection Smart Diode

LMS3635 - 3.5A Buck Regulator

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Rev. C

Sheet Title: TIDA-01432 E1 Power Schematic.SchDoc

Engineer: H.Bovenzi

Drawn By: DTP1 E1

Assembly Variant: N/A

File: TIDA-01432 E1 Power Schematic.SchDoc

Designed for: Not for Public Release

Mod. Date: 8/8/2017

Sheet: 6

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Sheet: 6
PCB Number: TIDA-01432
PCB Rev. E1

Variant/Label Table

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<tr>
<th>Variant</th>
<th>Label Text</th>
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<td>TIDA-01432</td>
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**Assembly Notes:**

- **ZZ1**
  - Variant notes are specified for PCB labels only.

- **ZZ2**
  - These assemblies are ESD sensitive. ESD precautions shall be observed.

- **ZZ3**
  - These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

- **ZZ4**
  - These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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